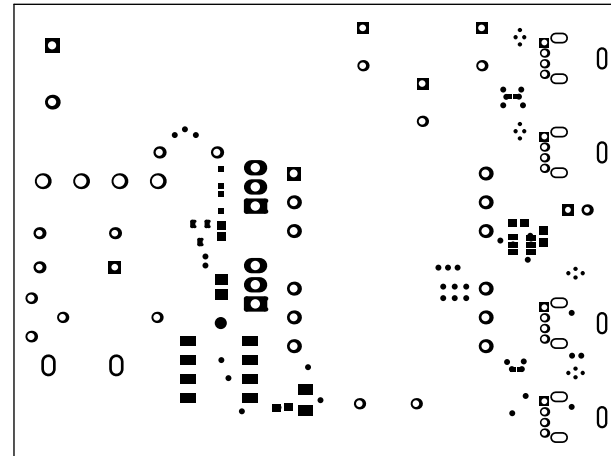
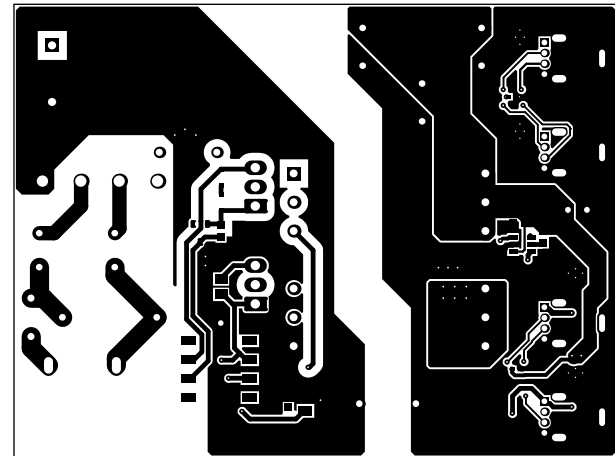


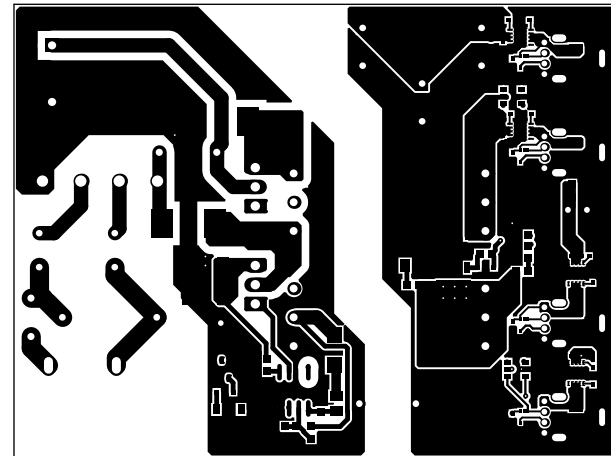
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10974 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | | | |
| PLOT NAME = Top Overlay | GENERATED : 8/5/2015 | 3:02:31 PM | TEXAS INSTRUMENTS |



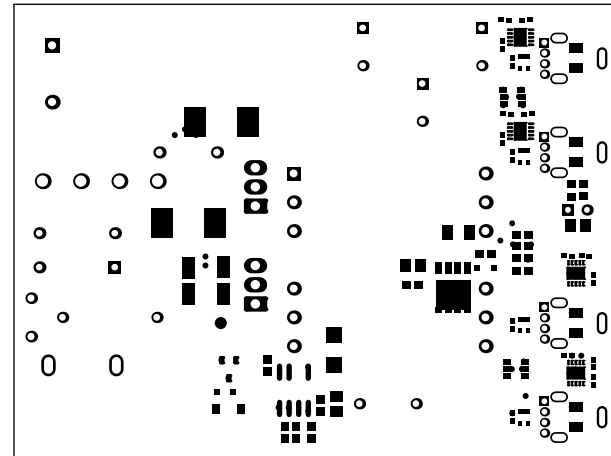
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10974 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | | | |
| PLOT NAME = Top Solder Mask | GENERATED : 8/5/2015 3:02:32 PM | TEXAS INSTRUMENTS | |



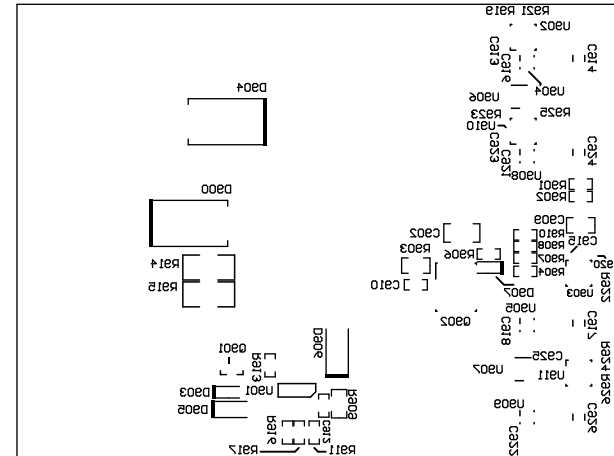
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10974 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | | | |
| PLOT NAME = Top Layer | GENERATED : 8/5/2015 3:02:33 PM | TEXAS INSTRUMENTS | |



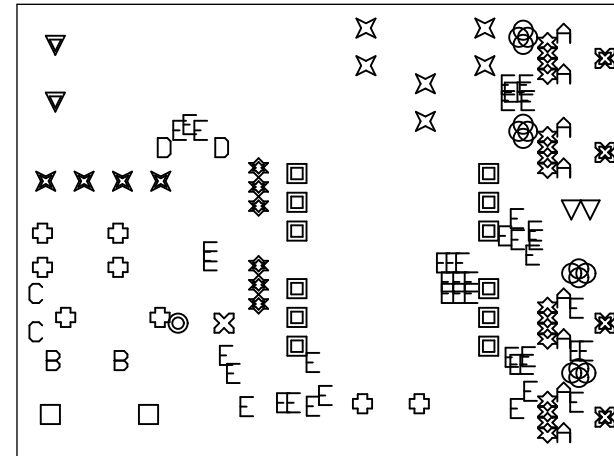
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10974 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | | | |
| PLOT NAME = Bottom Layer | GENERATED : 8/5/2015 3:02:34 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10974 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 8/5/2015 3:02:34 PM | TEXAS INSTRUMENTS | |

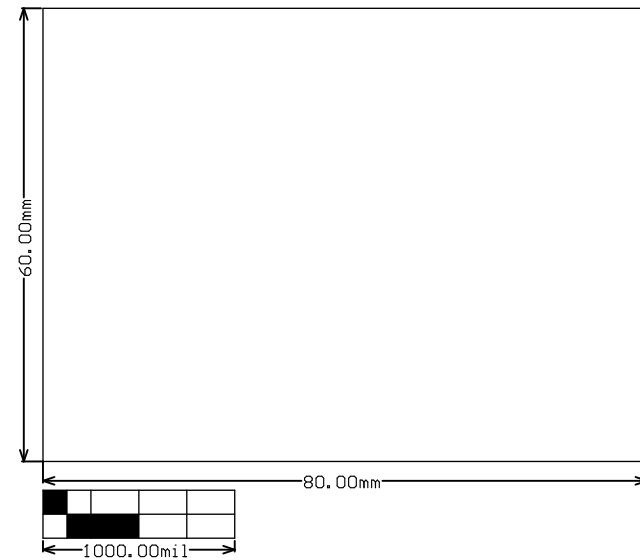


| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10974 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | | | |
| PLOT NAME = Bottom Overlay | GENERATED : 8/5/2015 | 3:02:35 PM | TEXAS INSTRUMENTS |



| Symbol | Quantity | Finished Hole Size | Plated | Hole Type |
|--------|-----------|---------------------|--------|-----------|
| □ | 2 | 118.11mil (3.000mm) | NPTH | Round |
| ○ | 16 | 7.87mil (0.200mm) | PTH | Round |
| E | 44 | 10.00mil (0.254mm) | PTH | Round |
| ⊗ | 1 | 30.00mil (0.762mm) | PTH | Round |
| ▽ | 2 | 31.00mil (0.787mm) | PTH | Round |
| ⊛ | 16 | 31.50mil (0.800mm) | PTH | Round |
| ⊗ | 6 | 35.00mil (0.889mm) | PTH | Round |
| ⊙ | 8 | 35.43mil (0.900mm) | PTH | Round |
| C | 2 | 37.40mil (0.950mm) | PTH | Round |
| D | 2 | 38.00mil (0.965mm) | PTH | Round |
| ■ | 12 | 41.34mil (1.050mm) | PTH | Round |
| ▽ | 2 | 43.31mil (1.100mm) | PTH | Round |
| ⊛ | 6 | 50.00mil (1.270mm) | PTH | Round |
| ⊗ | 4 | 59.06mil (1.500mm) | PTH | Round |
| ⊙ | 1 | 30.00mil (0.762mm) | PTH | Slot |
| ⊗ | 4 | 31.50mil (0.800mm) | PTH | Slot |
| ⊙ | 8 | 39.37mil (1.000mm) | PTH | Slot |
| B | 2 | 47.24mil (1.200mm) | PTH | Slot |
| | 138 Total | | | |

| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10974 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | | | |
| PLOT NAME = Drill Drawing | GENERATED : 8/5/2015 | 3:02:36 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10974 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | | | |
| PLOT NAME = Board Dimensions | GENERATED : 8/5/2015 | 3:02:37 PM | TEXAS INSTRUMENTS |

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